

STC AGENDA
Tuesday, October 5, 2004
1:30 – 5:00PM

1) Introductions and Roster modifications

2) April meeting minutes approval

2 Old business

3 New business

3.1 Review of ANSI J/STD-002-B

3.1.1 J-STD-002B Status

Dave Hillman reported that the IPC 5-23b committee has voted to begin work on the J-STD-002C revision effort. The 3 areas of focus for the revision are review/disposition of J-STD-002B comments, Pb-free solderability parameters, and validity of the wetting balance test method. The committee will discuss status of this DOE activity and plans for work. Inclusion of Pb-free solders/parameters a key area for the team to address.

This DOE activity is happening now. Updates will be discussed.

3.2 Possible replacements for steam pre-conditioning

Committee members have agreed that an area for future work is the replacement of steam pre-conditioning. Investigation of industry data and other pre-condition methods in use will be needed. Mr. Hillman has indicated that he will support this activity.

3.3 Gauge R&R for wetting balance test

The wetting balance test method is currently listed in ANSI/J-STD-002 under the section "Tests without Established Accept/Reject Criterion". Input from Dave Hillman was that the IPC committee discussed the options of either validating or removing the wetting balance method as an accepted method. Team needs to discuss plans/timing for future work.

4 Next meeting

5 Adjournment

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